

Product Change Notification - JAON-22CDLC928

Date: 31 Jan 2018
Product Category: 8-bit PIC Microcontrollers; Interface- Serial Peripherals; Interface- Controller Area Network (CAN)
Notification subject: CCB 3000 Final Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 28L SSOP package.
Notification text: **PCN Status:**
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 28L SSOP package.

Pre Change:

Assembled at MTAI using palladium coated copper (PdCu) bond wire.

Post Change:

Assembled at MTAI using palladium coated copper (PdCu) bond wire or assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand (HQ) / MTAI	Microchip Technology Thailand (HQ) / MTAI	Microchip Technology Thailand Branch (MMT)
Wire material	PdCu Wire	PdCu Wire	CuPdAu Wire
Die attach material	3280	3280	3280
Molding compound material	G600	G600	G600
Lead frame material	CDA194	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:
February 28, 2018 (date code: 1809)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2017				-->	January 2018					February 2018			
	27	28	29	30		01	02	03	04	05	06	07	08	09
Initial PCN Issue Date	X													
Qual Report Availability									X					
Final PCN Issue Date									X					
Estimated Implementation Date														X

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:
July 6, 2017: Issued initial notification.
January 31, 2018: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 28, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-22CDLC928_Qual_Report.pdf](#)
 - [PCN_JAON-22CDLC928_Affected CPN.pdf](#)
 - [PCN_JAON-22CDLC928_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22CDLC928
CATALOG_PART_NBR
HA1930-I/SS
HA1930T-I/SS
HA4315T-I/SS
HA4315T-I/SS022
MCP23016-I/SS
MCP23016T-I/SS
MCP23017-E/SS
MCP23017T-E/SS
MCP23S17-E/SS
MCP23S17T-E/SS
MCP25625-E/SS
MCP25625T-E/SS
PIC16F570-E/SS
PIC16F570-I/SS
PIC16F570T-I/SS
PIC16F57-E/SS
PIC16F57-I/SS
PIC16F57T-E/SS
PIC16F57T-I/SS
PIC16F57T-I/SS024
PIC16F57T-I/SS025
PIC16F57T-I/SS027
PIC16F72-E/SS
PIC16F72-I/SS
PIC16F72-I/SS085
PIC16F72T-E/SS
PIC16F72T-I/SS
PIC16F72T-I/SS085
PIC16F737-I/SS
PIC16F737T-I/SS
PIC16F73-E/SS
PIC16F73-I/SS
PIC16F73T-E/SS
PIC16F73T-I/SS
PIC16F73T-I/SS155
PIC16F73T-I/SSC15
PIC16F767-E/SS
PIC16F767-I/SS
PIC16F767T-I/SS
PIC16F76-E/SS
PIC16F76-I/SS
PIC16F76T-E/SS
PIC16F76T-I/SS
PIC16F873A-E/SS
PIC16F873A-I/SS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22CDLC928
CATALOG_PART_NBR
PIC16F873AT-I/SS
PIC16F876A-E/SS
PIC16F876A-I/SS
PIC16F876AT-E/SS
PIC16F876AT-I/SS
PIC16F876AT-I/SSC36
PIC16F882-E/SS
PIC16F882-I/SS
PIC16F882T-E/SS
PIC16F882T-I/SS
PIC16F883-E/SS
PIC16F883-I/SS
PIC16F883-I/SS046
PIC16F883-I/SS063
PIC16F883-I/SS064
PIC16F883T-E/SS
PIC16F883T-I/SS
PIC16F883T-I/SS022
PIC16F883T-I/SS063
PIC16F883T-I/SS064
PIC16F883T-I/SS070
PIC16F883T-I/SS071
PIC16F886-E/SS
PIC16F886-I/SS
PIC16F886T-E/SS
PIC16F886T-I/SS
PIC16F886T-I/SS026
PIC16F886T-I/SS052
PIC16F886T-I/SS056
PIC16F886T-I/SSC07
PIC16F913-E/SS
PIC16F913-I/SS
PIC16F913T-E/SS
PIC16F913T-I/SS
PIC16F913T-I/SS025
PIC16F913T-I/SS027
PIC16F913T-I/SS032
PIC16F916-E/SS
PIC16F916-I/SS
PIC16F916-I/SS035
PIC16F916T-I/SS
PIC16F916T-I/SS028
PIC16F916T-I/SS029
PIC16F916T-I/SS031
PIC16F916T-I/SS033

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22CDLC928
CATALOG_PART_NBR
PIC16F916T-I/SS035
PIC16LF72-I/SS
PIC16LF72T-I/SS
PIC16LF737-I/SS
PIC16LF737T-I/SS
PIC16LF737T-I/SS021
PIC16LF73-I/SS
PIC16LF73T-I/SS
PIC16LF767-I/SS
PIC16LF767T-I/SS
PIC16LF76-I/SS
PIC16LF76T-I/SS
PIC16LF873A-I/SS
PIC16LF873AT-I/SS
PIC16LF876A-I/SS
PIC16LF876AT-I/SS
PIC16LF876AT-I/SSC26
PIC18F2221-E/SS
PIC18F2221-I/SS
PIC18F2221T-I/SS
PIC18F2321-E/SS
PIC18F2321-I/SS
PIC18F2321T-E/SS
PIC18LF2221-I/SS
PIC18LF2221T-I/SS
PIC18LF2321-I/SS
PIC18LF2321T-I/SS
PS501T-I/SSC01
PS501T-I/SSC05